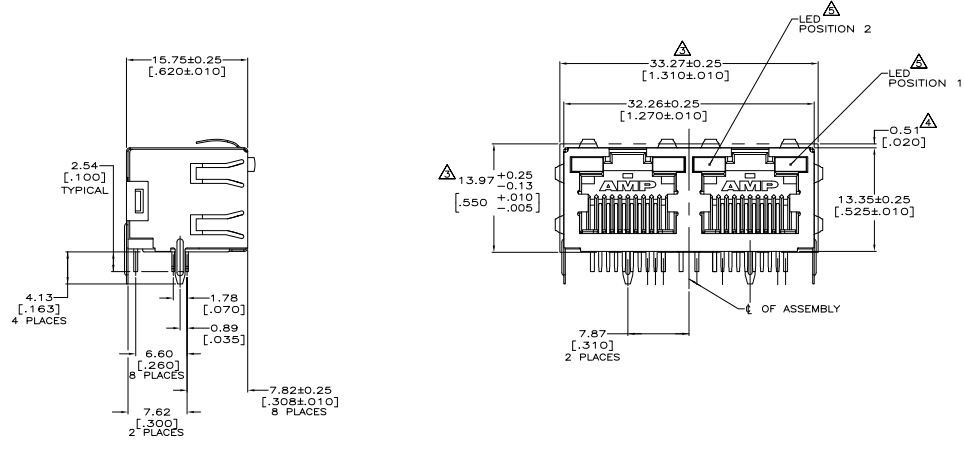
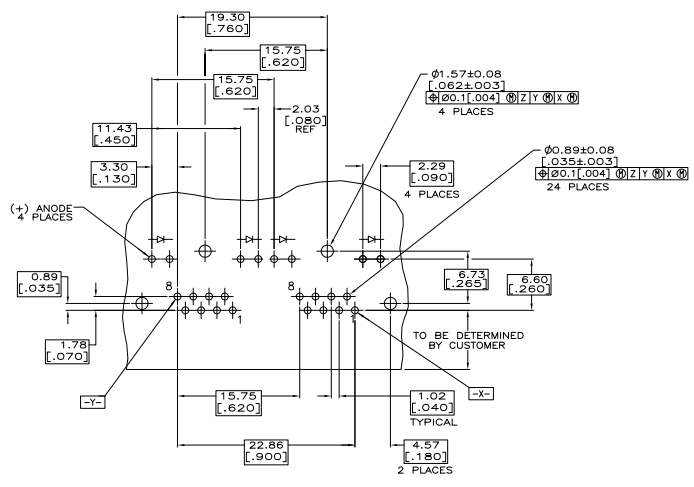


REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
A		REV PER EC 0511-0201-04			15MAY2005 LV SF
A1		REVISED PER ECO-09-024927			10NOV09 KK/AEG



- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.8µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89µm[.0003500] THICK Sn/Cu OVER 2.03µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

INDICATOR COLOR FOR EACH HOUSING	POSITION 2	POSITION 1	PART NUMBER
GREEN	GREEN	GREEN	6364173-5
YELLOW	GREEN	GREEN	6364173-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNED BY	DATE	REVISED BY	DATE
WESTMAN	10/20/05	WESTMAN	10/20/05
DESIGNED BY	DATE	REVISED BY	DATE
WESTMAN	10/20/05	WESTMAN	10/20/05
DESIGNED BY	DATE	REVISED BY	DATE
WESTMAN	10/20/05	WESTMAN	10/20/05

INVERTED MODULAR JACK ASSEMBLY, 1X2, PANEL GROUND, SHELDED, NO MOUNTING LEADS, WITH LEADS.

114-2154

100779 6364173

CUSTOMER DRAWING